

ABSTRACT

3 A method of forming a hermetically sealed MEMS package
4 includes a step of providing a supporting GaAs substrate
5 with at least one contact for the MEMS device on the surface
6 of the supporting substrate and forming a cantilever on the
7 surface of the supporting substrate positioned to come into
8 electrical engagement with the contact in one orientation.
9 A metal seal ring is fixed to the surface of the supporting
10 substrate circumferentially around the contact and the
11 cantilever. A cavity is etched in a silicon chip to form a
12 cap member. A metal seal ring is fixed to the cap member
13 around the cavity. The package is hermetically sealed by
14 reflowing a solder alloy, positioned between the two seal
15 rings, in an inert environment without the use of flux.